

December 2014

### FQPF9P25YDTU

### P-Channel QFET® MOSFET

-250 V, -6 A, 620  $m\Omega$ 

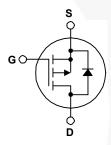
### **Description**

produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, audio amplifier, • 100% Avalanche Tested DC motor control, and variable switching power applications.

#### **Features**

- This P-Channel enhancement mode power MOSFET is -6 A, -250 V,  $R_{DS(on)}$  = 620 m $\Omega$  (Max.) @  $V_{GS}$  = -10 V,
  - Low Gate Charge (Typ. 29 nC)
  - Low Crss (Typ. 27 pF)





### Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted.

Symbol	Parameter		FQPF9P25YDTU	Unit		
V <sub>DSS</sub>	Drain-Source Voltage		-250	V		
I <sub>D</sub>	Drain Current - Continuous (T <sub>C</sub> = 25°C)		-6.0	Α		
	- Continuous (T <sub>C</sub> = 100°C)		-3.9	А		
I <sub>DM</sub>	Drain Current - Pulsed	(Note 1)	-24			
V <sub>GSS</sub>	Gate-Source Voltage		± 30	V		
E <sub>AS</sub>	Single Pulsed Avalanche Energy	(Note 2)	650	mJ		
I <sub>AR</sub>	Avalanche Current	(Note 1)	-6.0	Α		
E <sub>AR</sub>	Repetitive Avalanche Energy	(Note 1)	5.0	mJ		
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	-5.5	V/ns		
$P_D$	Power Dissipation (T <sub>C</sub> = 25°C)		50	W		
	- Derate above 25°C		0.4	W/°C		
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +150	°C		
T <sub>L</sub>	Maximum lead temperature for soldering, 1/8" from case for 5 seconds.		300	°C		

#### **Thermal Characteristics**

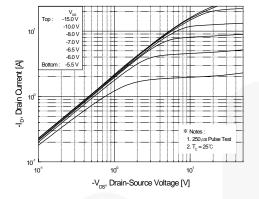
Symbol	Parameter	FQPF9P25YDTU	Unit		
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	2.5	°C/W		
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	62.5	°C/W		

Packag	je Marki	ng and Ord	ering lı	nforma	ation						
		Top Mark	Pack	220F Tube		Reel	Size	Tape Width		Quantity	
		FQPF9P25	TO-2 (Y-for			N/A		N/A		50 units	
Electric	cal Chai	racteristics	T <sub>C</sub> = 25°C	C unless other	erwise noted.						
Symbol		Parameter			Test Conditions		Min.	Тур.	Max	. Unit	
Off Cha	aracterist	ice									
BV <sub>DSS</sub>		rce Breakdown Vol	tane	V <sub>CC</sub> = 0	) V, I <sub>D</sub> = -250 μA		-250			V	
ΔBV <sub>DSS</sub>			Towns and the				200			•	
/ $\Delta T_J$	Coefficient		oltage Temperature $I_D = -250 \mu A$ , Referenced to 25°C			25°C		-0.2		V/°C	
I <sub>DSS</sub>	Zoro Coto	7 0 1 1/1 5 1 0 1			V <sub>DS</sub> = -250 V, V <sub>GS</sub> = 0 V				-1	μА	
	Zero Gate	Zero Gate Voltage Drain Current		V <sub>DS</sub> = -200 V, T <sub>C</sub> = 125°C					-10	μΑ	
I <sub>GSSF</sub>	Gate-Body	/ Leakage Current,	Forward	V <sub>GS</sub> = -	30 V, V <sub>DS</sub> = 0 V				-100	nA	
I <sub>GSSR</sub>	Gate-Body	y Leakage Current, Reverse		$V_{GS} = 3$	80 V, V <sub>DS</sub> = 0 V				100	nA	
On Cha	racteristi	ice									
V <sub>GS(th)</sub>		nreshold Voltage		V <sub>DS</sub> = V	<sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250 μA		-3.0		-5.0	V	
R <sub>DS(on)</sub>		rain-Source			<sub>GS</sub> = -10 V, I <sub>D</sub> = -3.0 A			0.48	0.62		
9 <sub>FS</sub>	Forward T	ransconductance		V <sub>DS</sub> = -	<sub>DS</sub> = -40 V, I <sub>D</sub> = -3.0 A			4.8		S	
Dvnam	ic Charac	cteristics		-1				+	1		
C <sub>iss</sub>	Input Capa			$V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0  MHz				910	1180	) pF	
C <sub>oss</sub>	Output Ca	pacitance						170	220	pF	
C <sub>rss</sub>	Reverse T	ransfer Capacitance		1.10 11.12				27	35	pF	
							1		1		
Switch	ing Chara	acteristics									
t <sub>d(on)</sub>	Turn-On D	elay Time		V <sub>DD</sub> = -	V <sub>DD</sub> = -125 V, I <sub>D</sub> = -9.4 A,			20	50	ns	
t <sub>r</sub>	Turn-On R	Rise Time		$R_G = 25 \Omega$				150	310	ns	
$t_{d(off)}$	Turn-Off D	elay Time						45	100	ns	
t <sub>f</sub>	Turn-Off F	all Time			(1)	lote 4)		65	140	ns	
Qg	Total Gate	Charge		V <sub>DS</sub> = -	200 V, I <sub>D</sub> = -9.4 A,			29	38	nC	
Q <sub>gs</sub>	Gate-Sour	ce Charge		$V_{GS} = -10 \text{ V}$ (Note 4)				7.6		nC	
Q <sub>gd</sub>	Gate-Drain	n Charge				lote 4)	/	14		nC	
				•			-//		•		
Drain-S	Source Di	ode Character	istics a	nd Maxi	imum Ratings						
Is	Maximum	mum Continuous Drain-Source Diode Forward Current						-6.0	Α		
I <sub>SM</sub>	Maximum	Pulsed Drain-Sour	ce Diode F	Diode Forward Current					-24	Α	
V <sub>SD</sub>	Drain-Sou	rce Diode Forward	Voltage	$V_{GS} = 0$	) V, I <sub>S</sub> = -6.0 A				-5.0	V	
t <sub>rr</sub>		Recovery Time		1	) V, I <sub>S</sub> = -9.4 A,			190		ns	
Q <sub>rr</sub>		Recovery Charge			= 100 A/μs			1.45		μС	
••				1				-			

# $Q_{rr}$

- 1. Repetitive rating : pulse-width limited by maximum junction temperature.
- 2. L = 28.9 mH, I $_{AS}$  = -6.0 A, V $_{DD}$  = -50 V, R $_{G}$  = 25  $\Omega$ , starting T $_{J}$  = 25°C. 3. I $_{SD}$  ≤ -9.4 A, di/dt ≤ 300 A/ $\mu$ s , V $_{DD}$  = BV $_{DSS}$ , starting T $_{J}$  = 25°C. 4. Essentially independent of operating temperature.

### **Typical Characteristics**



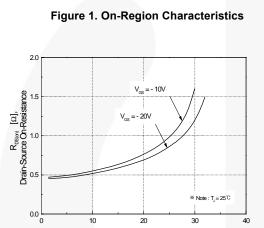


Figure 3. On-Resistance Variation vs. **Drain Current and Gate Voltage** 

-I<sub>D</sub>, Drain Current [A]

30

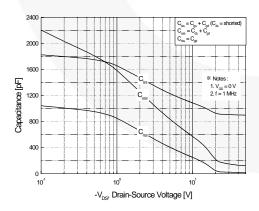


Figure 5. Capacitance Characteristics

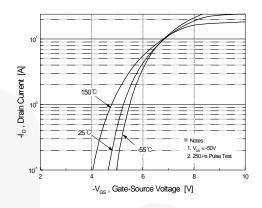


Figure 2. Transfer Characteristics

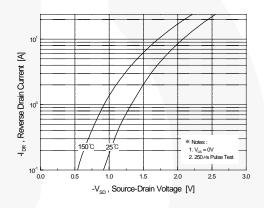


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

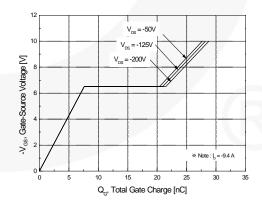
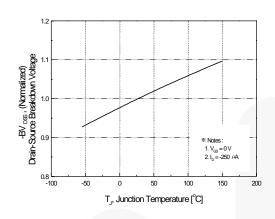


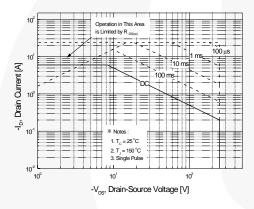
Figure 6. Gate Charge Characteristics



Typical Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



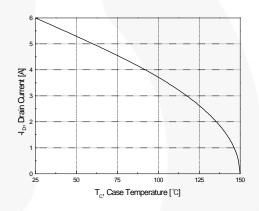


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

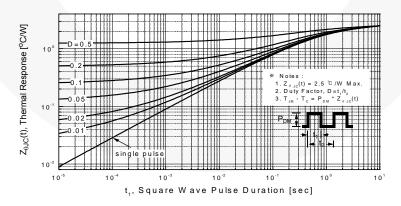


Figure 11. Transient Thermal Response Curve

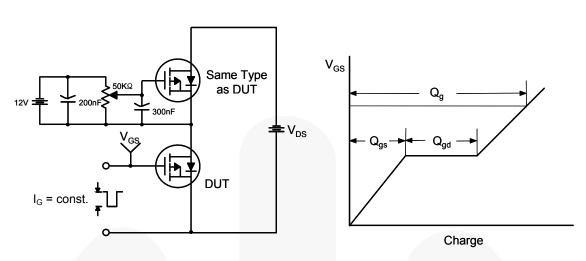


Figure 12. Gate Charge Test Circuit & Waveform

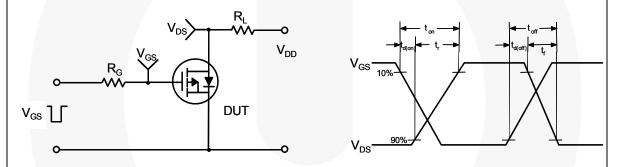


Figure 13. Resistive Switching Test Circuit & Waveforms

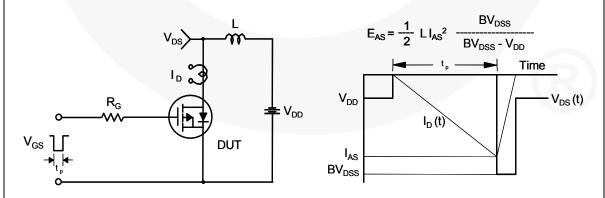
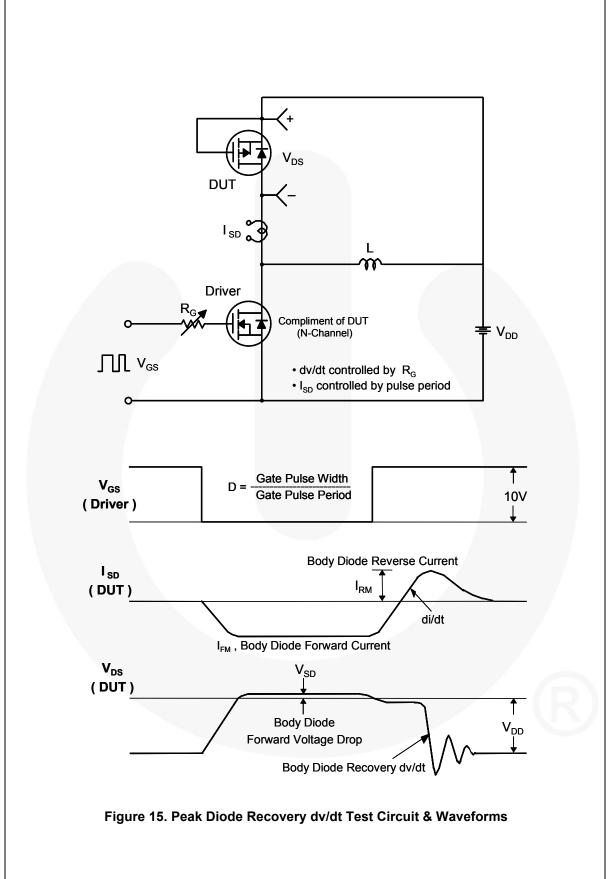
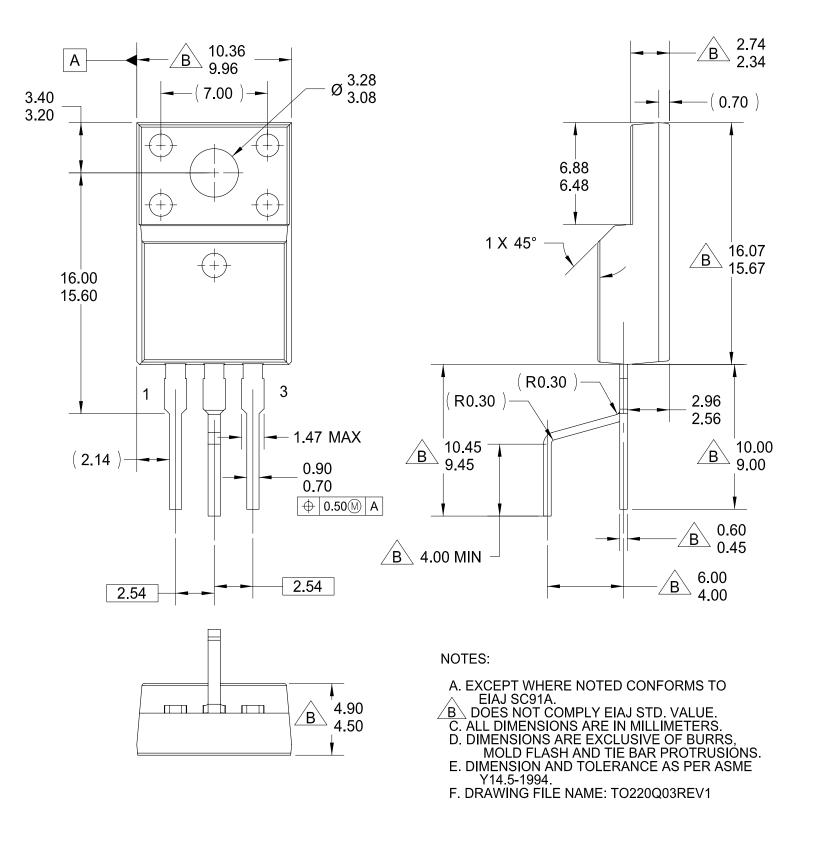


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms









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